

LAYER-STACK	Sym	Иo	Mils	MM	Qty	Plated
01-16	+	1	12	0.30	387	YES
01-20	×	2	24	0.60	10	YES
	□	3	35	0.90	2	NOT
	♦	4	40	1.02	2	YES
	X	5	52	1.32	36	YES

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PCB:

- HASI, finish

- Green LPI solder mask

- White silkscreen

- Panelization is at discretion of manufacturer.

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- Top layer

- Top layer

- Second layer (qnd)

- Third layer (pur)

- Bottom layer

- Top soldermask

- Top soldermask

- Top soldermask

- Top soldermask

- Top solder paste mask

- Board outline is square. Outlines drawn inside the square (top right, bottom left) should be ignored.

Assembly:

- CBA is to be labeled on bottom side as shoun

- Line 2: Name of manufacture

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- YY: Year of manufacture

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- XXXXX Unique serial number for the week of manufacture
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Clay G5.1 2015-09-24 GBH